

# T-1 (3mm) BI-LEVEL LED INDICATOR

Part Number: L-7104FG/1Y1GD

Yellow Green

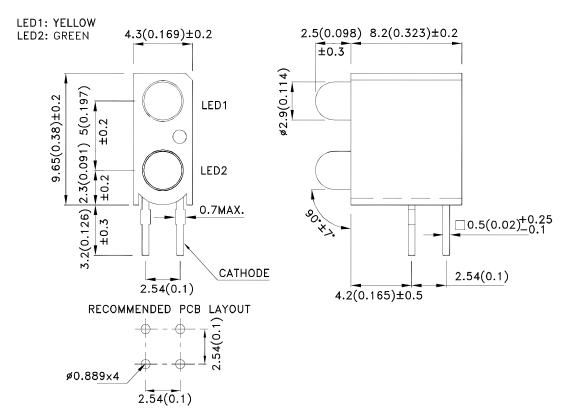
#### **Features**

- Pre-trimmed leads for pc mounting.
- Black case enhances contrast ratio.
- Wide viewing angle.
- High reliability life measured in years.
- Housing UL rating:94V-0.
- Housing material: type 66 nylon.
- RoHS compliant.

### **Descriptions**

- The Yellow source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Yellow Light
- The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

# **Package Dimensions**



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.25(0.01") unless otherwise noted.
- 3. Lead spacing is measured where the leads emerge from the package.
  4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

SPEC NO: DSAI2904 **REV NO: V.2B DATE: DEC/06/2014** PAGE: 1 OF 6 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: P.Cheng ERP: 1102013230

### **Selection Guide**

Part No.	Dice	Lens Type	lv (mcd) [2] @ 10mA		Viewing Angle [1]
		,	Min.	Тур.	201/2
L-7104FG/1Y1GD	Yellow (GaAsP/GaP)	Yellow Diffused	8	15	40°
L-7 1041 G/11 1GD	Green (GaP)	Green Diffused	10	25	40°

#### Notes:

- 1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value. 2. Luminous intensity/ luminous Flux: +/-15%.
- 3. Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Yellow Green	590 565		nm	IF=20mA
λD [1]	Dominant Wavelength	Yellow Green	588 568		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Yellow Green	35 30		nm	IF=20mA
С	Capacitance	Yellow Green	20 15		pF	V <sub>F</sub> =0V;f=1MHz
VF [2]	Forward Voltage	Yellow Green	2.1 2.2	2.5 2.5	V	IF=20mA
lr	Reverse Current	Yellow Green		10 10	uA	V <sub>R</sub> = 5V

- 1.Wavelength: +/-1nm.
- Forward Voltage: +/-0.1V.
   Wavelength value is traceable to the CIE127-2007 compliant national standards.
- Excess driving current and/or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

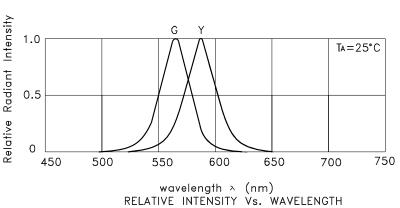
# Absolute Maximum Ratings at TA=25°C

Parameter	Yellow	Green	Units		
Power dissipation	75	62.5	mW		
DC Forward Current	30	25	mA		
Peak Forward Current [1]	140	140	mA		
Reverse Voltage	5 V				
Operating / Storage Temperature	-40°C To +85°C				
Lead Solder Temperature [2]	260°C For 3 Seconds				
Lead Solder Temperature [3]	260°C For 5 Seconds				

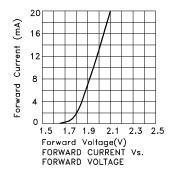
### Notes:

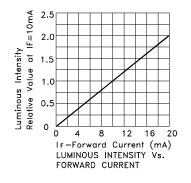
- 1. 1/10 Duty Cycle, 0.1ms Pulse Width.
   2. 2mm below package base.
   5mm below package base.

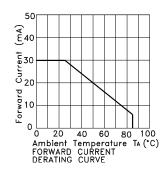
SPEC NO: DSAI2904 **REV NO: V.2B** DATE: DEC/06/2014 PAGE: 2 OF 6 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: P.Cheng ERP: 1102013230

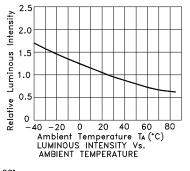


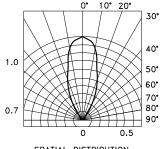
## L-7104FG/1Y1GD Yellow







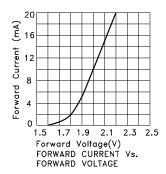


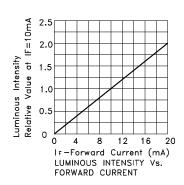


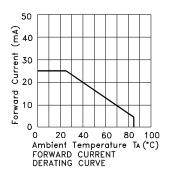
SPATIAL DISTRIBUTION

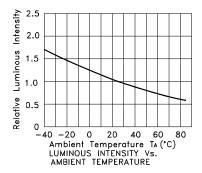
SPEC NO: DSAI2904 **REV NO: V.2B** DATE: DEC/06/2014 PAGE: 3 OF 6 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: P.Cheng ERP: 1102013230

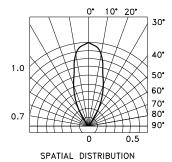
# Green



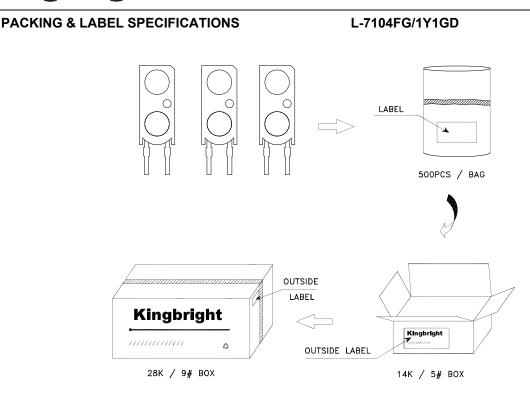








SPEC NO: DSAI2904 REV NO: V.2B DATE: DEC/06/2014 PAGE: 4 OF 6
APPROVED: WYNEC CHECKED: Allen Liu DRAWN: P.Cheng ERP: 1102013230





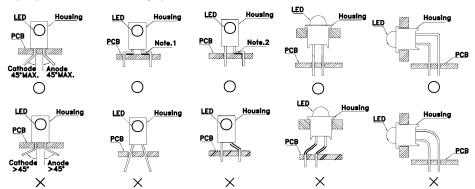
### Terms and conditions for the usage of this document

- 1. The information included in this document reflects representative usage scenarios and is intended for technical reference only.
- 2. The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
- 3. When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.
- 4. The information in this document applies to typical usage in consumer electronics applications. If customer's application has special reliability requirements or have life-threatening liabilities, such as automotive or medical usage, please consult with Kingbright representative for further assistance.
- 5. The contents and information of this document may not be reproduced or re-transmitted without permission by Kingbright.
- 6.All design applications should refer to Kingbright application notes available at <a href="http://www.kingbright.com/application">http://www.kingbright.com/application</a> notes

SPEC NO: DSAI2904 REV NO: V.2B DATE: DEC/06/2014 PAGE: 5 OF 6
APPROVED: WYNEC CHECKED: Allen Liu DRAWN: P.Cheng ERP: 1102013230

### **PRECAUTIONS**

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead—forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.

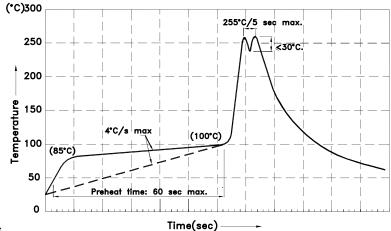


" $\bigcirc$  " Correct mounting method "imes" Incorrect mounting method

2. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.



- 3. The tip of the soldering iron should never touch the lens epoxy.
- 4. Through—hole LEDs are incompatible with reflow soldering.
- 5. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.
- 6. Recommended Wave Soldering Profiles:



Notes:

1.Recommend pre—heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum

solder bath temperature of 260°C 2.Peak wave soldering temperature between 245°C  $\sim 255$ °C for 3 sec (5 sec max).

3.Do not apply stress to the epoxy resin while the temperature is above  $85^{\circ}\text{C}$ .

4.Fixtures should not incur stress on the component when mounting and during soldering process.

5.SAC 305 solder alloy is recommended.

6.No more than one wave soldering pass.

SPEC NO: DSAI2904 REV NO: V.2B DATE: DEC/06/2014 PAGE: 6 OF 6

APPROVED: WYNEC CHECKED: Allen Liu DRAWN: P.Cheng ERP: 1102013230